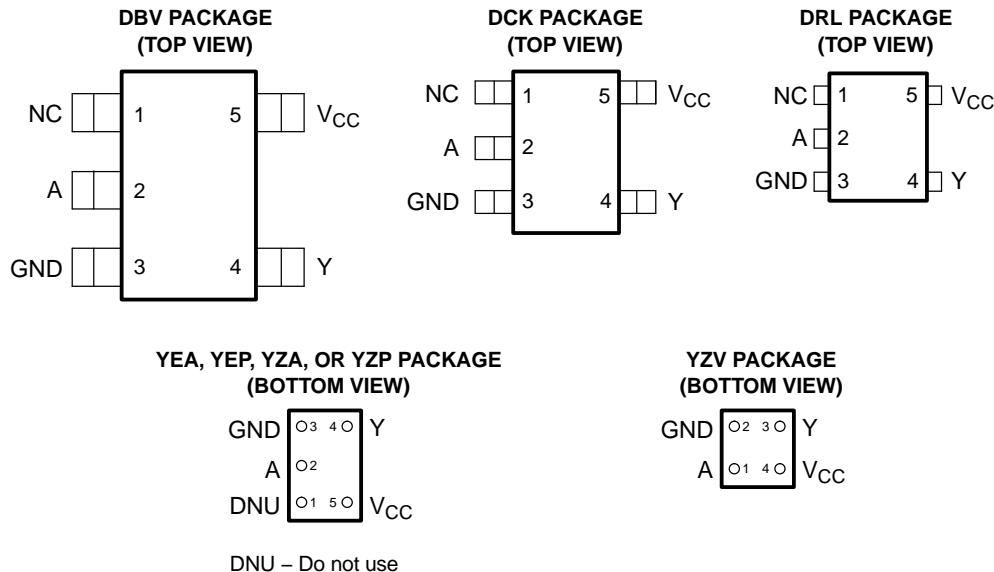


FEATURES

- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 3.3 ns at 3.3 V
- Low Power Consumption, 10- μ A Max I_{CC}
- ± 24 -mA Output Drive at 3.3 V
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

This single inverter gate is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1G04 performs the Boolean function $Y = \bar{A}$.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar, NanoFree are trademarks of Texas Instruments.

ORDERING INFORMATION

TA	PACKAGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽²⁾
-40°C to 85°C	NanoStar™ – WCSP (DSBGA) 0.17-mm Small Bump – YEA	Reel of 3000	---CC_
	NanoFree™ – WCSP (DSBGA) 0.17-mm Small Bump – YZA (Pb-free)		
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP		
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)		
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YZV (Pb-free)		PREVIEW
SOT (SOT-23) – DBV	Reel of 3000	SN74LVC1G04DBVR	C04_
	Reel of 250	SN74LVC1G04DBVT	
SOT (SC-70) – DCK	Reel of 3000	SN74LVC1G04DCKR	CC_
	Reel of 250	SN74LVC1G04DCKT	
SOT (SOT-553) – DRL	Reel of 4000	SN74LVC1G04DRLR	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

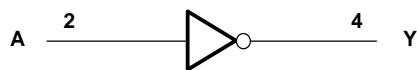
(2) DBV/DCK/DRL: The actual top-side marking has one additional character that designates the assembly/test site.

YEA/YZA, YEP/YZP/YZV: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

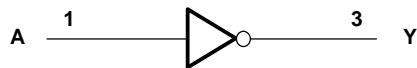
FUNCTION TABLE

INPUT A	OUTPUT Y
H	L
L	H

**LOGIC DIAGRAM (POSITIVE LOGIC)
(DBV, DCK, DRL, YEA, YEP, YZA, AND YZP PACKAGE)**



**LOGIC DIAGRAM (POSITIVE LOGIC)
(YZV PACKAGE)**



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	6.5	V
V_I	Input voltage range	-0.5	6.5	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	6.5	V
V_O	Voltage range applied to any output in the high or low state ⁽²⁾⁽³⁾	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$	-50	mA
I_{OK}	Output clamp current	$V_O < 0$	-50	mA
I_O	Continuous output current		± 50	mA
	Continuous current through V_{CC} or GND		± 100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	DBV package	206	°C/W
		DCK package	252	
		DRL package	142	
		YEA/YZA package	154	
		YEP/YZP package	132	
		YZV package	TBD	
T_{stg}	Storage temperature range	-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The value of V_{CC} is provided in the recommended operating conditions table.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

SN74LVC1G04
SINGLE INVERTER GATE

SCES214S—APRIL 1999—REVISED OCTOBER 2005



Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage	Operating	1.65	5.5	V
		Data retention only	1.5		
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	1.7		
		V _{CC} = 3 V to 3.6 V	2		
		V _{CC} = 4.5 V to 5.5 V	0.7 × V _{CC}		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	0.7		
		V _{CC} = 3 V to 3.6 V	0.8		
		V _{CC} = 4.5 V to 5.5 V	0.3 × V _{CC}		
V _I	Input voltage		0	5.5	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65 V	−4		mA
		V _{CC} = 2.3 V	−8		
		V _{CC} = 3 V	−16		
		V _{CC} = 4.5 V	−24		
I _{OL}	Low-level output current	V _{CC} = 1.65 V	4		mA
		V _{CC} = 2.3 V	8		
		V _{CC} = 3 V	16		
		V _{CC} = 4.5 V	24		
Δt/Δv	Input transition rise or fall rate	V _{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V	20		ns/V
		V _{CC} = 3.3 V ± 0.3 V	10		
		V _{CC} = 5 V ± 0.5 V	5		
T _A	Operating free-air temperature		−40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}	I _{OH} = -100 μ A		1.65 V to 5.5 V	V _{CC} - 0.1			V
	I _{OH} = -4 mA		1.65 V	1.2			
	I _{OH} = -8 mA		2.3 V	1.9			
	I _{OH} = -16 mA		3 V	2.4			
	I _{OH} = -24 mA			2.3			
	I _{OH} = -32 mA		4.5 V	3.8			
V _{OL}	I _{OL} = 100 μ A		1.65 V to 5.5 V		0.1		V
	I _{OL} = 4 mA		1.65 V		0.45		
	I _{OL} = 8 mA		2.3 V		0.3		
	I _{OL} = 16 mA		3 V	0.4			
	I _{OL} = 24 mA			0.55			
	I _{OL} = 32 mA		4.5 V	0.55			
I _I	A input	V _I = 5.5 V or GND		0 to 5.5 V		± 5	μ A
I _{off}		V _I or V _O = 5.5 V		0		± 10	μ A
I _{CC}	V _I = 5.5 V or GND	I _O = 0		1.65 V to 5.5 V		10	μ A
ΔI_{CC}	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND			3 V to 5.5 V		500	μ A
C _i	V _I = V _{CC} or GND			3.3 V		3.5	pF

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

Switching Characteristics

over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Y	2	6.4	1	4.2	0.7	3.3	0.7	3.1	ns

Switching Characteristics

over recommended operating free-air temperature range, C_L = 30 pF or 50 pF (unless otherwise noted) (see [Figure 2](#))

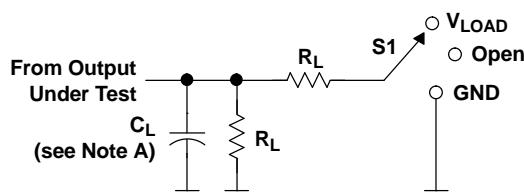
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Y	3	7.5	1.4	5.2	1	4.2	1	3.7	ns

Operating Characteristics

T_A = 25°C

PARAMETER	TEST CONDITIONS	V _{CC} = 1.8 V		V _{CC} = 2.5 V		V _{CC} = 3.3 V		V _{CC} = 5 V		UNIT
		TYP		TYP		TYP		TYP		
C _{pd}	Power dissipation capacitance	f = 10 MHz	16		18		18		20	pF

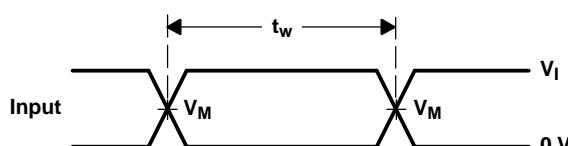
PARAMETER MEASUREMENT INFORMATION



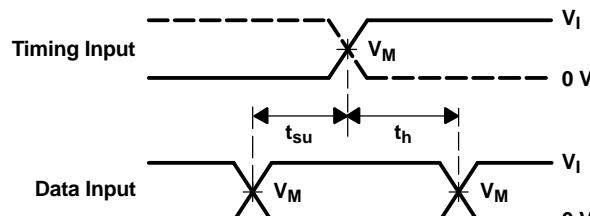
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT

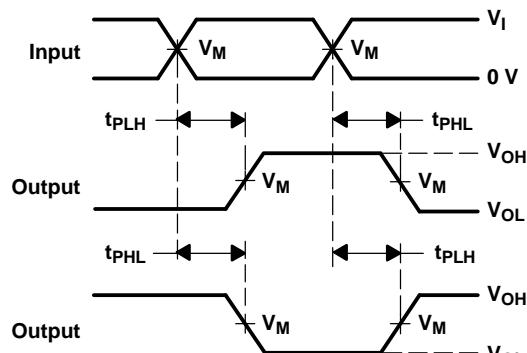
V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
$1.8 \text{ V} \pm 0.15 \text{ V}$	V_{CC}	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	$1 \text{ M}\Omega$	0.15 V
$2.5 \text{ V} \pm 0.2 \text{ V}$	V_{CC}	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	$1 \text{ M}\Omega$	0.15 V
$3.3 \text{ V} \pm 0.3 \text{ V}$	3 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	15 pF	$1 \text{ M}\Omega$	0.3 V
$5 \text{ V} \pm 0.5 \text{ V}$	V_{CC}	$\leq 2.5 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	$1 \text{ M}\Omega$	0.3 V



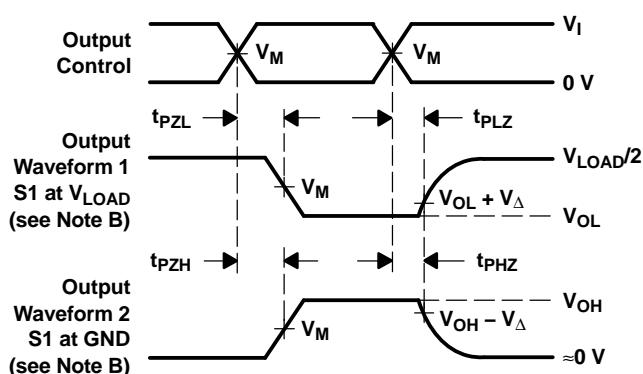
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



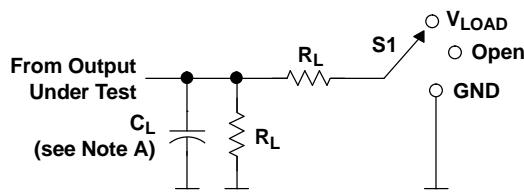
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10 \text{ MHz}$, $Z_O = 50 \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

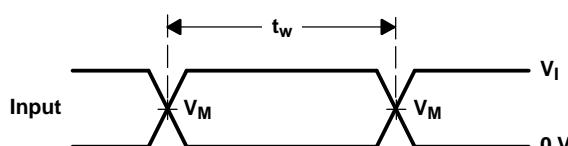
PARAMETER MEASUREMENT INFORMATION



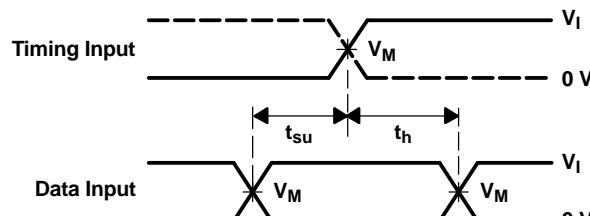
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT

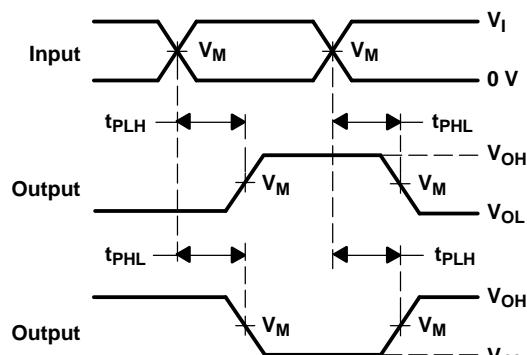
V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
$1.8 \text{ V} \pm 0.15 \text{ V}$	V_{CC}	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5 \text{ V} \pm 0.2 \text{ V}$	V_{CC}	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
$3.3 \text{ V} \pm 0.3 \text{ V}$	3 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$5 \text{ V} \pm 0.5 \text{ V}$	V_{CC}	$\leq 2.5 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 Ω	0.3 V



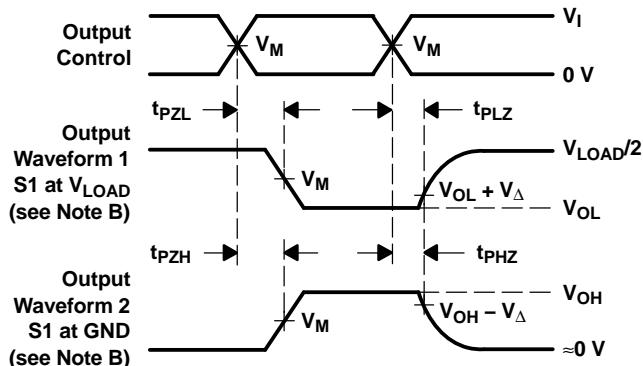
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10 \text{ MHz}$, $Z_O = 50 \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC1G04DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G04DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G04DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G04DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G04DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G04DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G04DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G04DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G04DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G04DCKTE4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G04DRLR	ACTIVE	SOP	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G04DRLRG4	ACTIVE	SOP	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G04YEAR	NRND	WCSP	YEA	5	3000	TBD	SNPB	Level-1-260C-UNLIM
SN74LVC1G04YEPR	NRND	WCSP	YEP	5	3000	TBD	SNPB	Level-1-260C-UNLIM
SN74LVC1G04YZAR	NRND	WCSP	YZA	5	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM
SN74LVC1G04YZPR	ACTIVE	WCSP	YZP	5	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM
SN74LVC1G04YZVR	ACTIVE	DSBGA	YZV	4	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

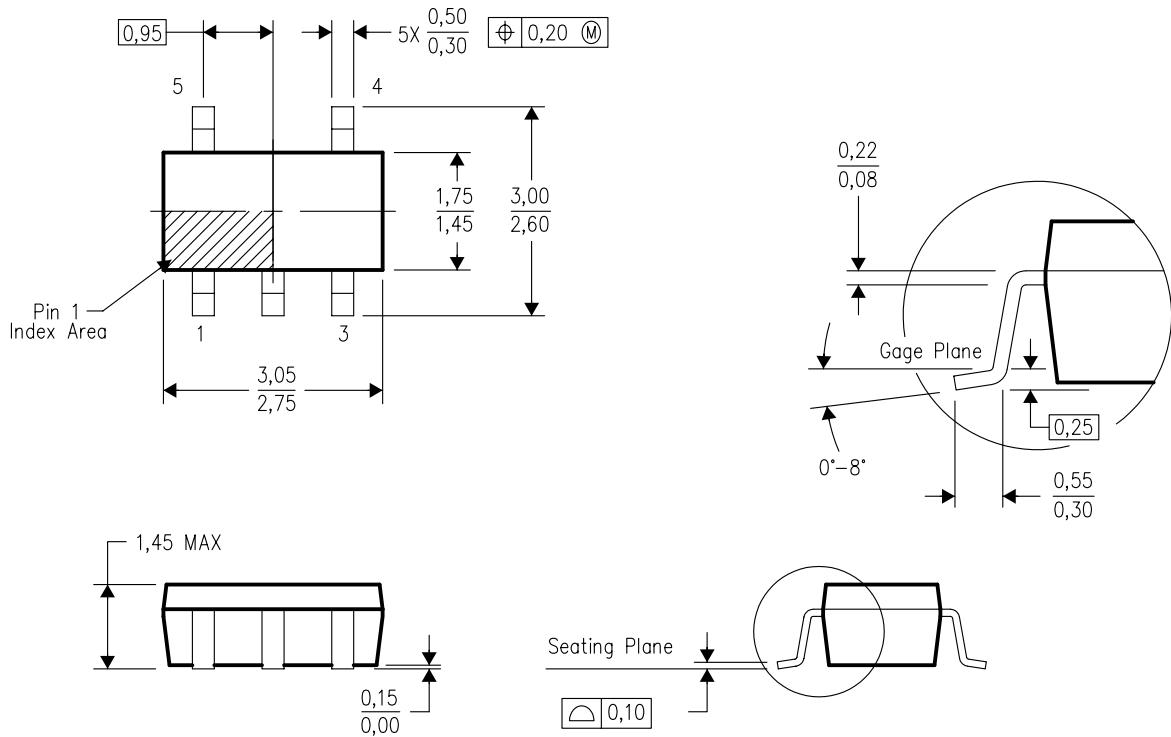
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



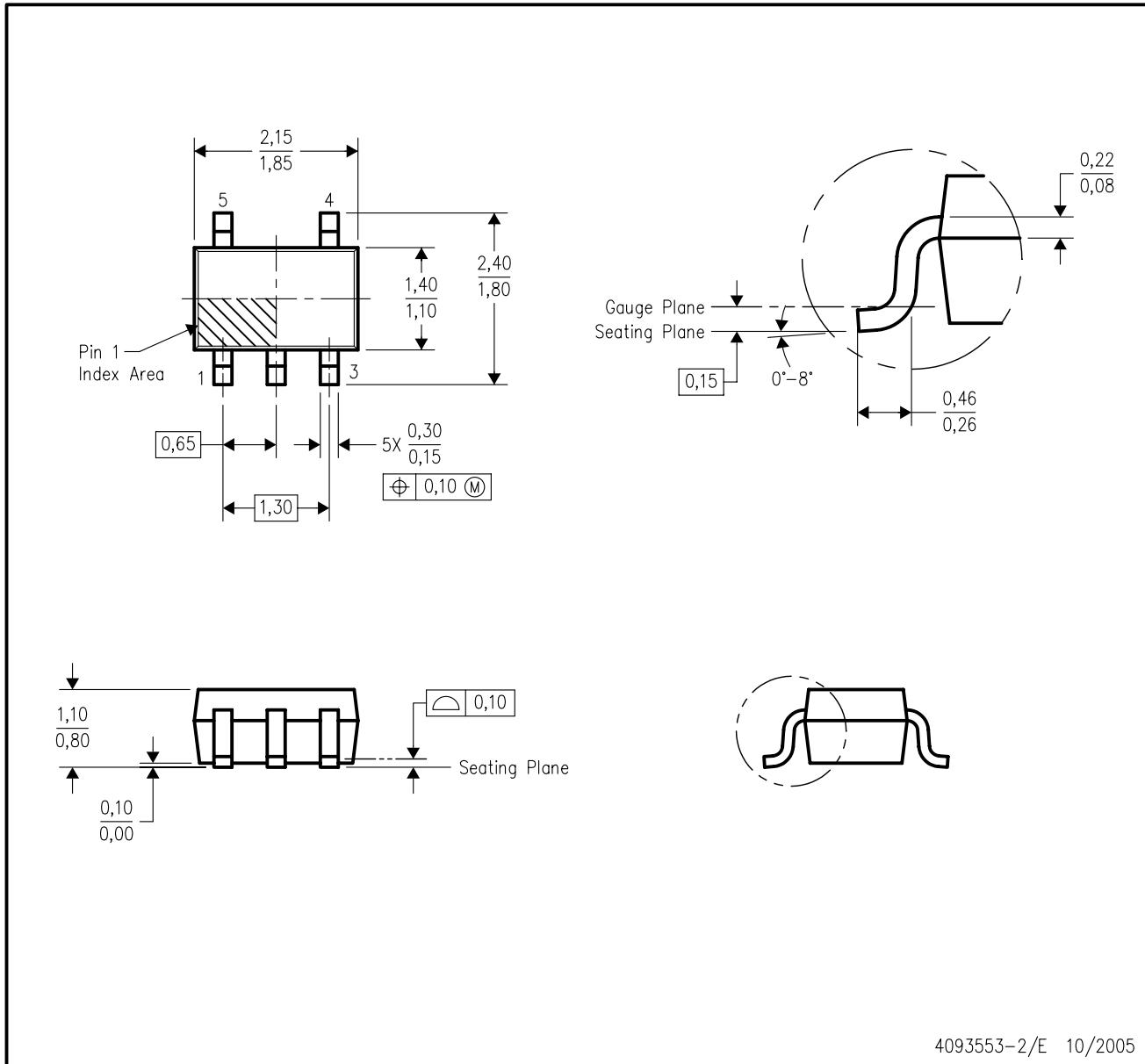
4073253-4/K 03/2006

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- Falls within JEDEC MO-178 Variation AA.

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



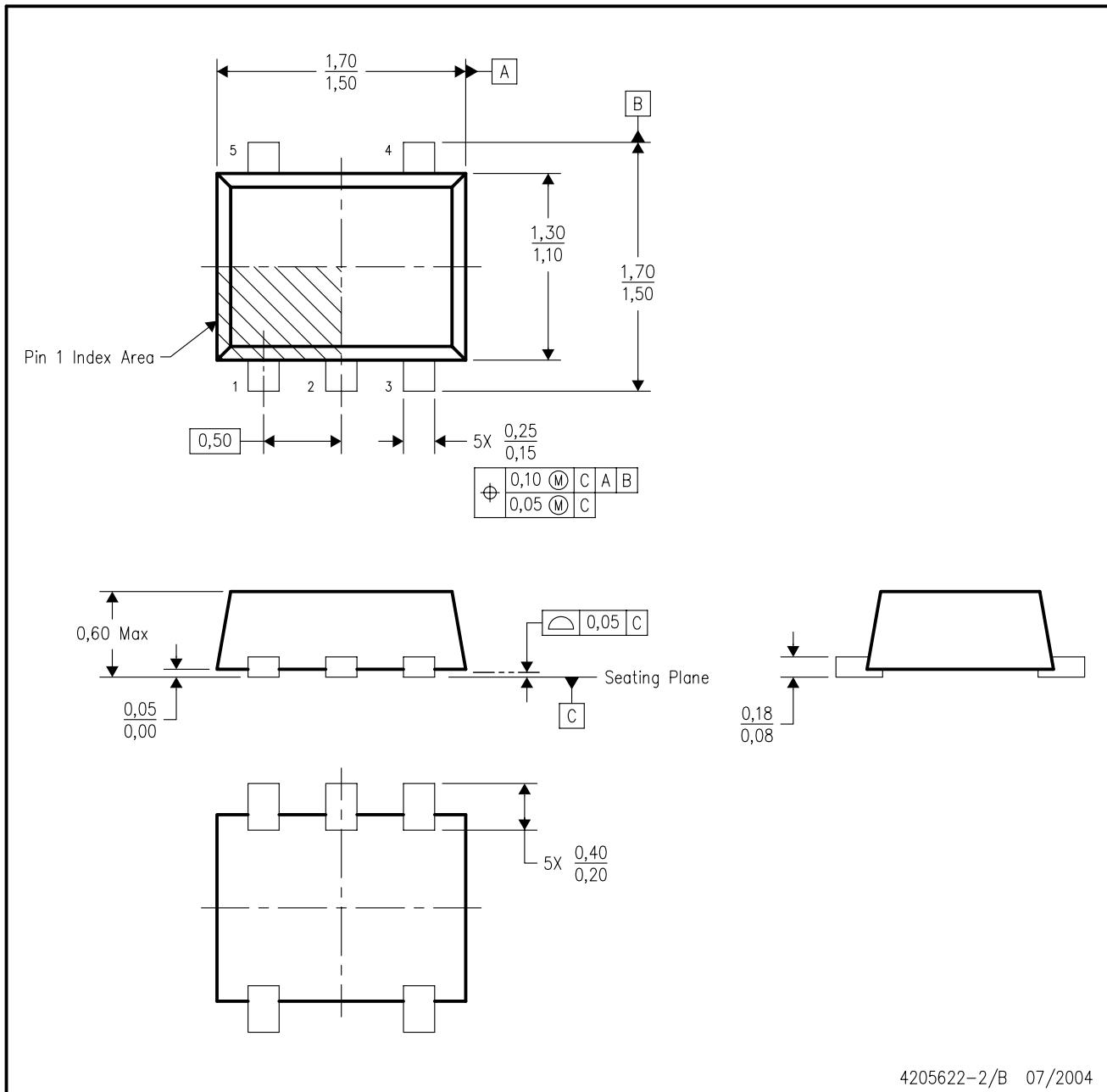
4093553-2/E 10/2005

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- Falls within JEDEC MO-203 variation AA.

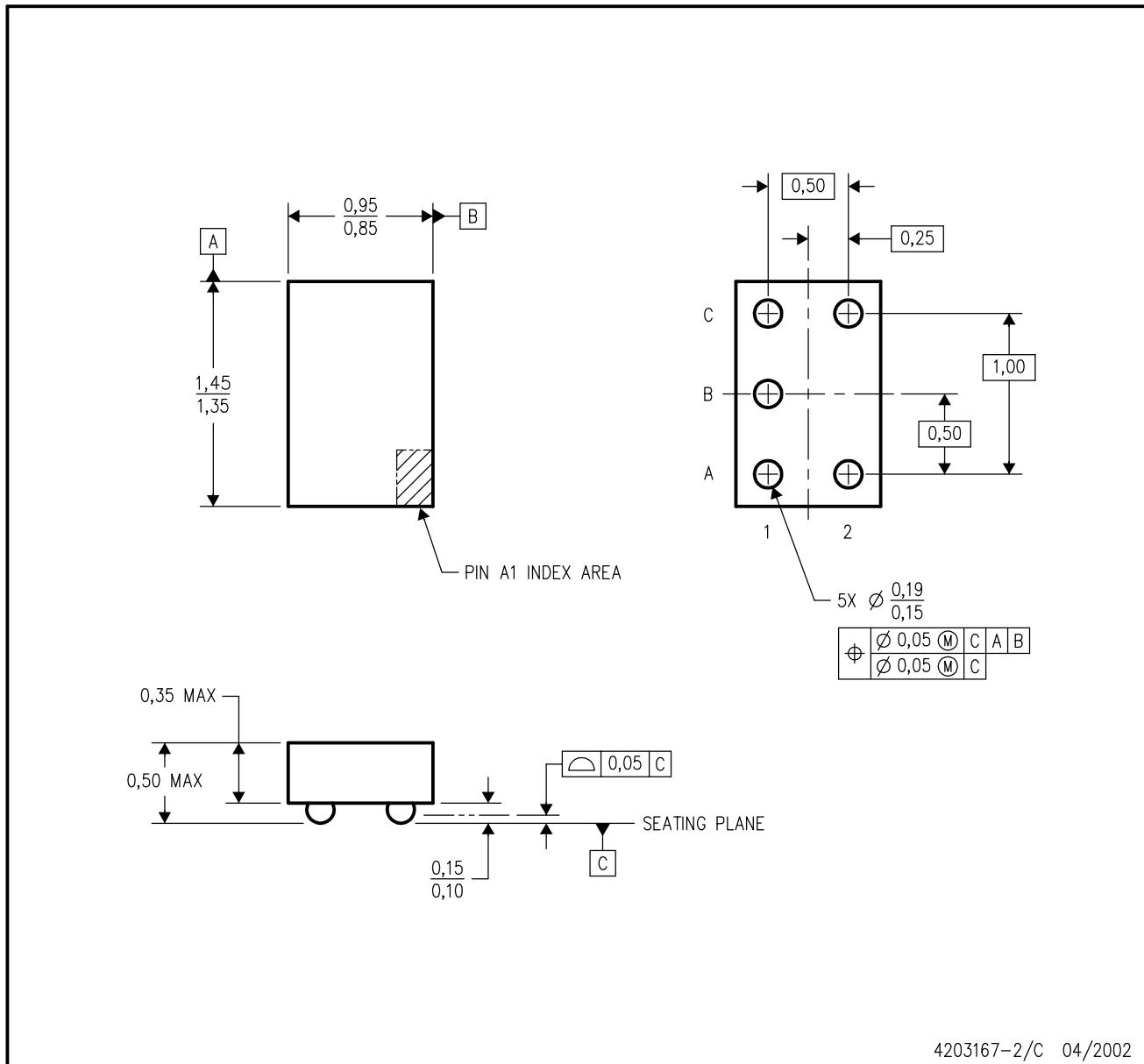
DRL (R-PDSO-N5)

PLASTIC SMALL OUTLINE



YEA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



4203167-2/C 04/2002

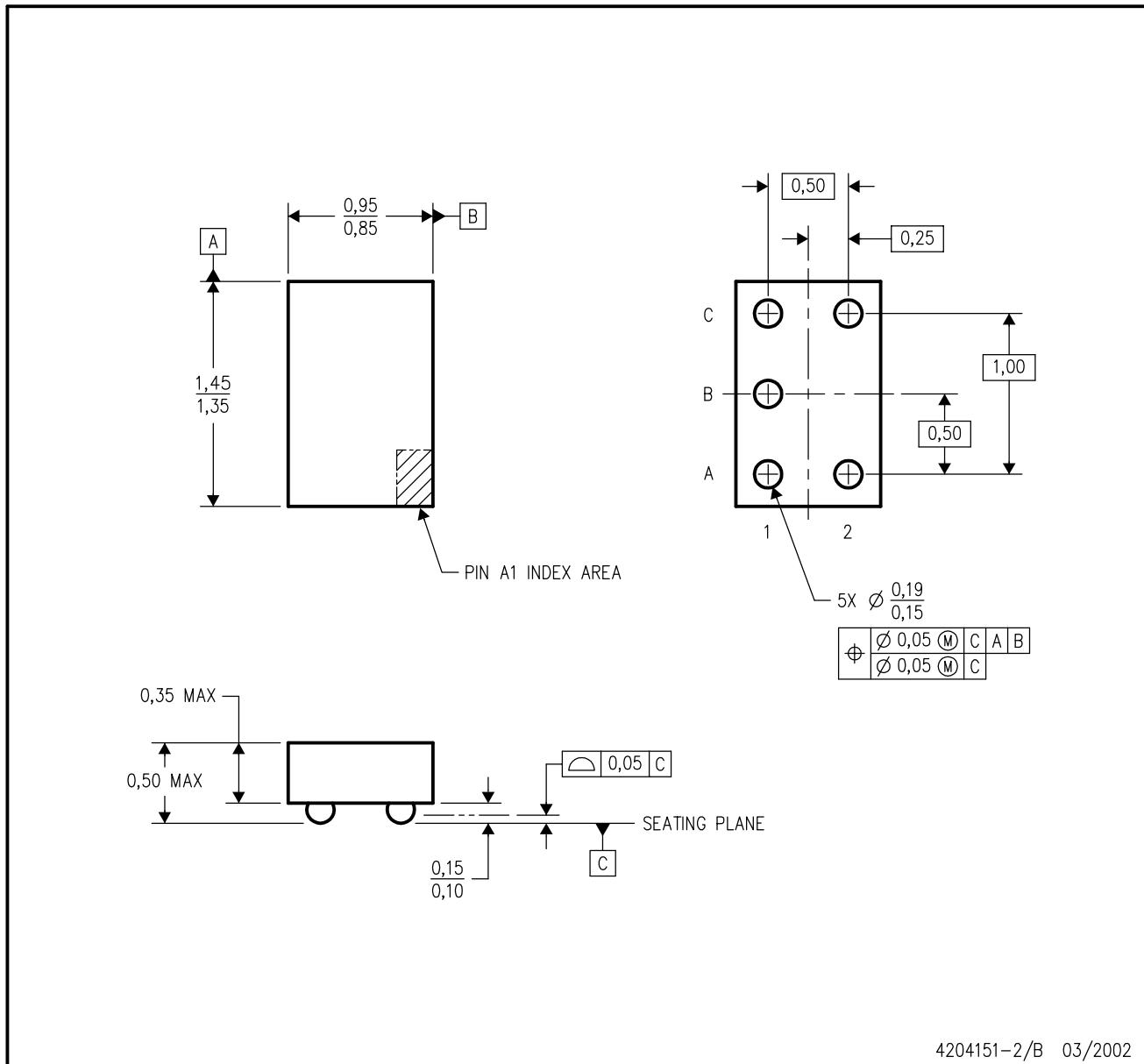
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- NanoStar™ package configuration.
- Package complies to JEDEC MO-211 variation EA.
- This package is tin-lead (SnPb). Refer to the 5 YZA package (drawing 4204151) for lead-free.

NanoStar is a trademark of Texas Instruments.

YZA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



4204151-2/B 03/2002

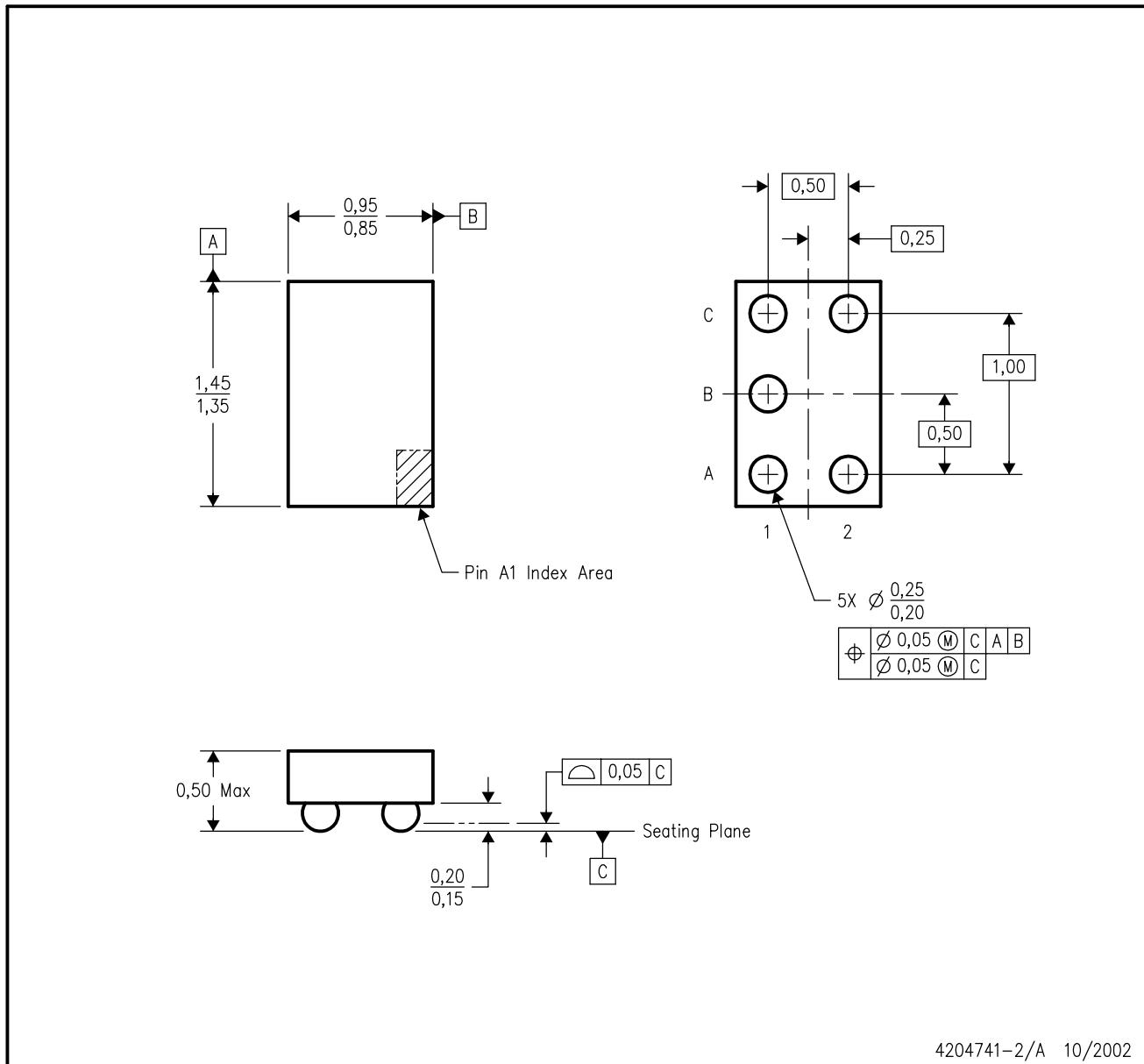
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- NanoFree™ package configuration.
- Package complies to JEDEC MO-211 variation EA.
- This package is lead-free. Refer to the 5 YEA package (drawing 4203167) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.

YZP (R-XBGA-N5)

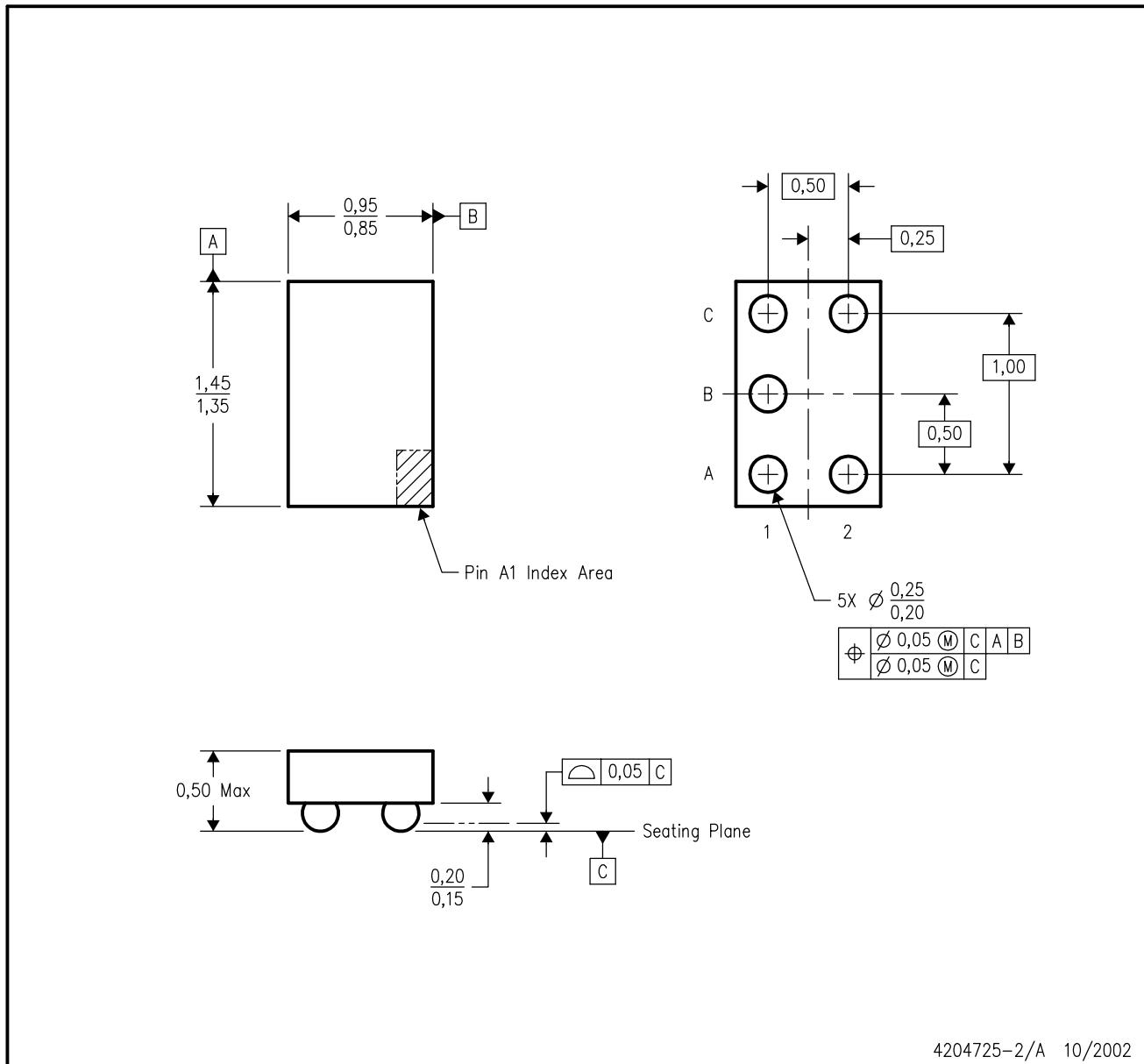
DIE-SIZE BALL GRID ARRAY



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YEP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



4204725-2/A 10/2002

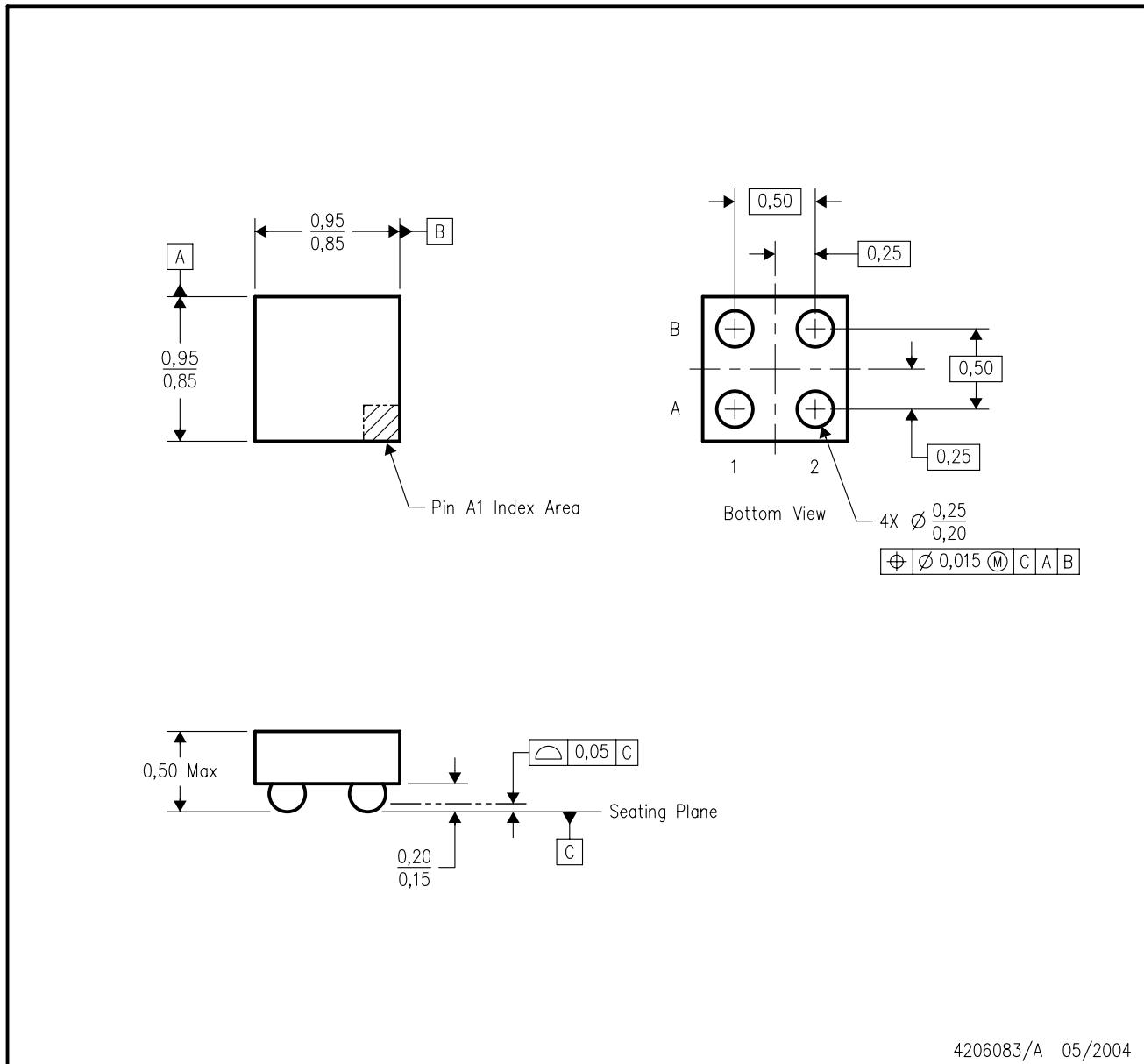
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- NanoStar™ package configuration.
- This package is tin-lead (SnPb). Refer to the 5 YZP package (drawing 4204741) for lead-free.

NanoStar is a trademark of Texas Instruments.

YZV (S-XBGA-N4)

DIE-SIZE BALL GRID ARRAY



NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- NanoFree™ package configuration.
- This package contains lead-free balls. Refer to the 4 YEV package (drawing 4206082) for tin-lead (SnPb) balls.

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